WAFER-PROCESSING TAPE

ABSTRACT

A wafer-processing tape, having a supporting substrate, a removable adhesive layer, and a single layer of an adhesive layer, which are laminated in this order, in which the adhesive layer is an adhesive layer which is used to crimp a semiconductor element to a wiring-adhered wiring member for external connection or another semiconductor element, and in which a difference in surface free energy between the face of the adhesive layer that has been peeled-off from the removable adhesive layer and the face that is not brought into contact with the removable adhesive layer is 10 mJ/m^2 or less.

Figure 1